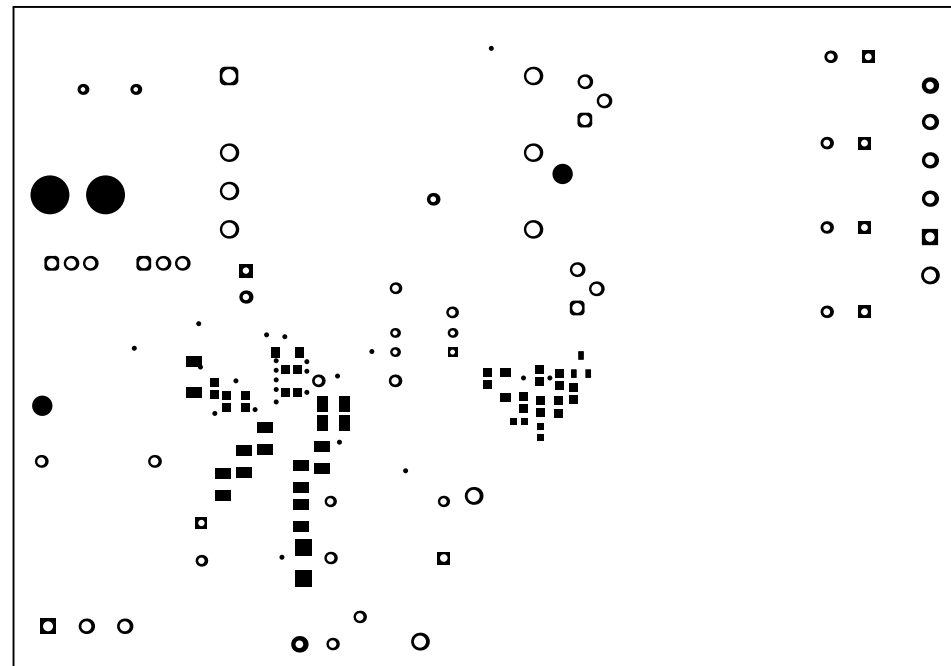
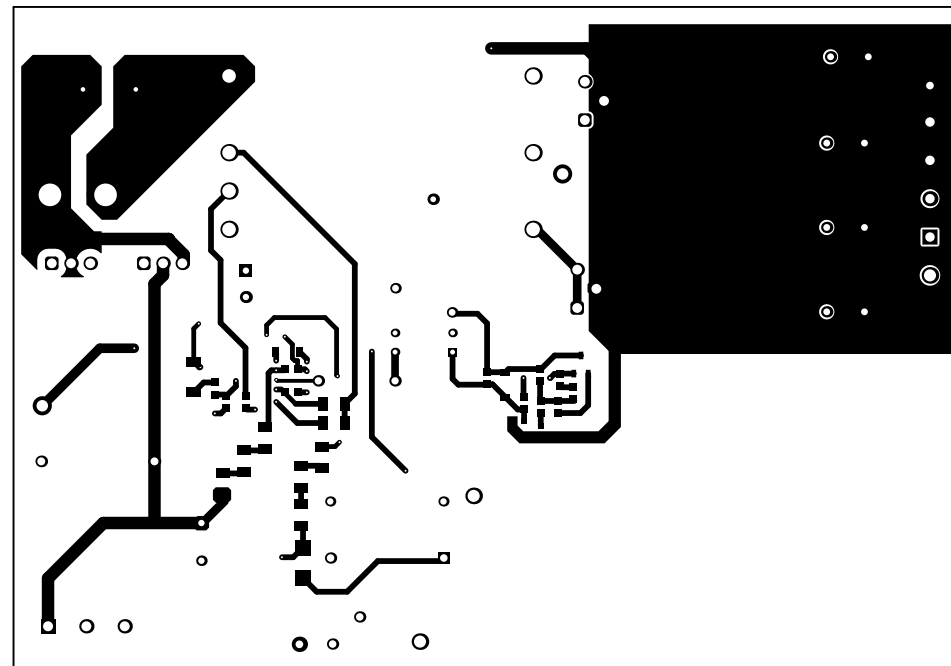


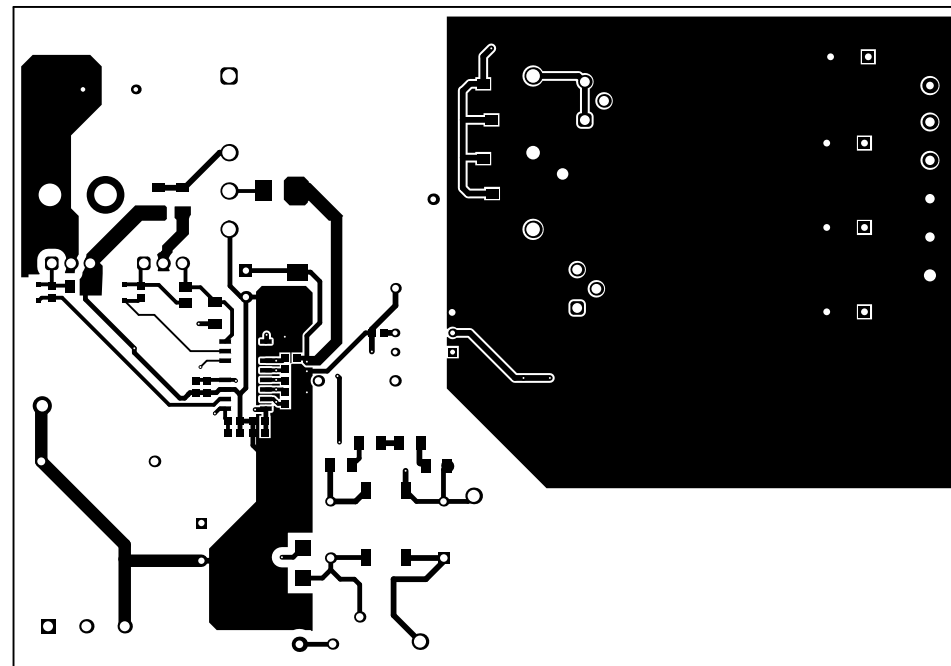
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 6/1/2017	3:00:00 PM	TEXAS INSTRUMENTS



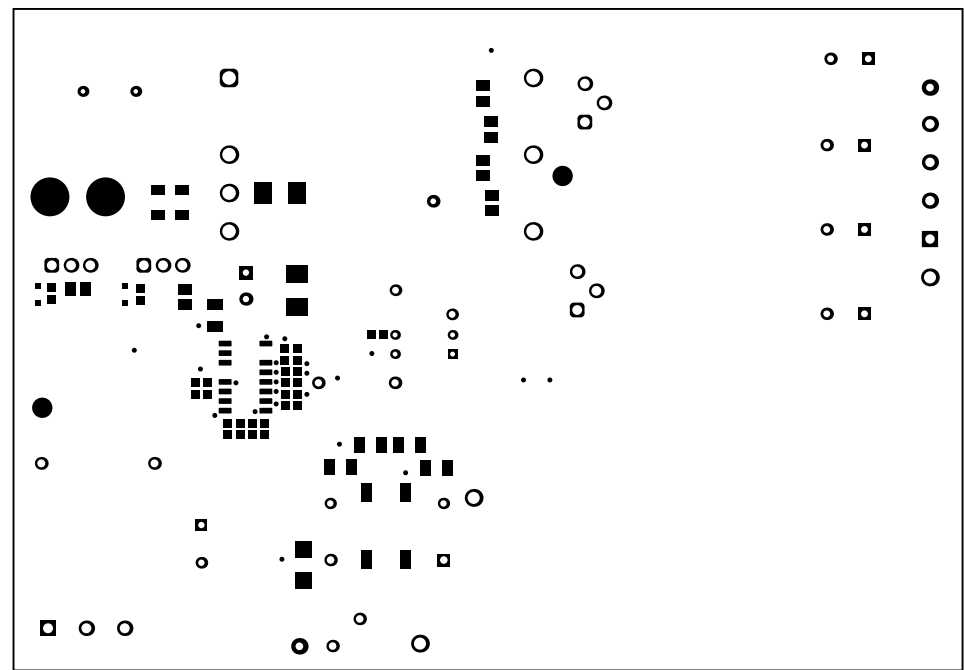
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 6/1/2017	3:00:02 PM	TEXAS INSTRUMENTS



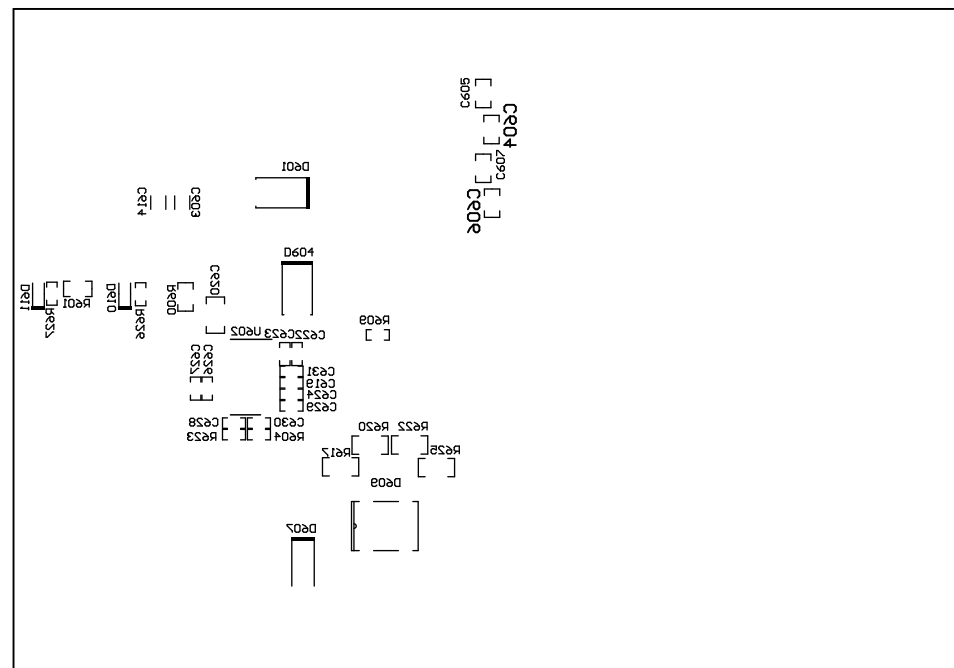
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 6/1/2017	3:00:03 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 6/1/2017	3:00:05 PM	TEXAS INSTRUMENTS

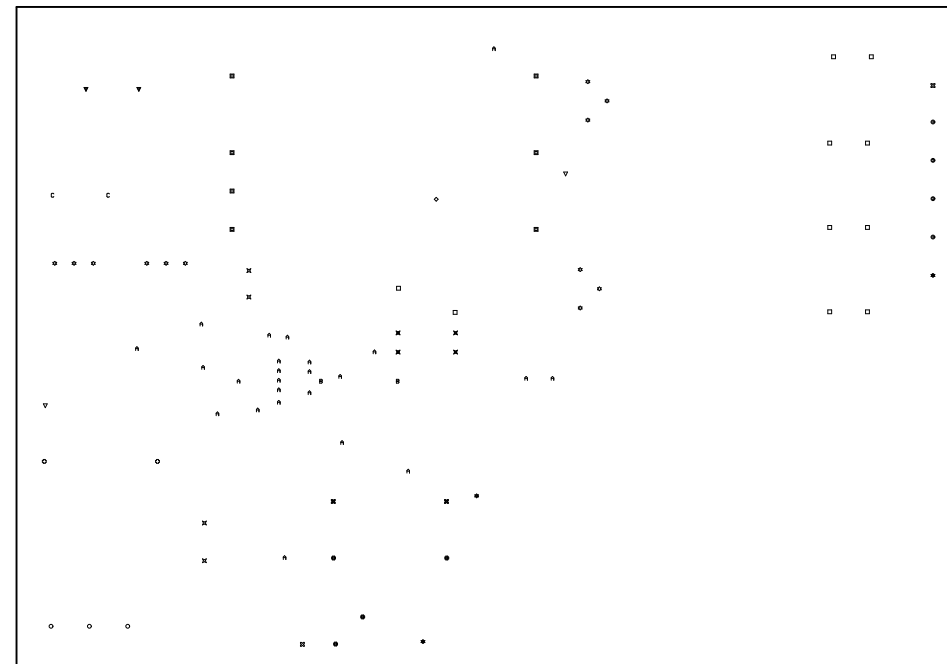


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/1/2017	3:00:06 PM	TEXAS INSTRUMENTS

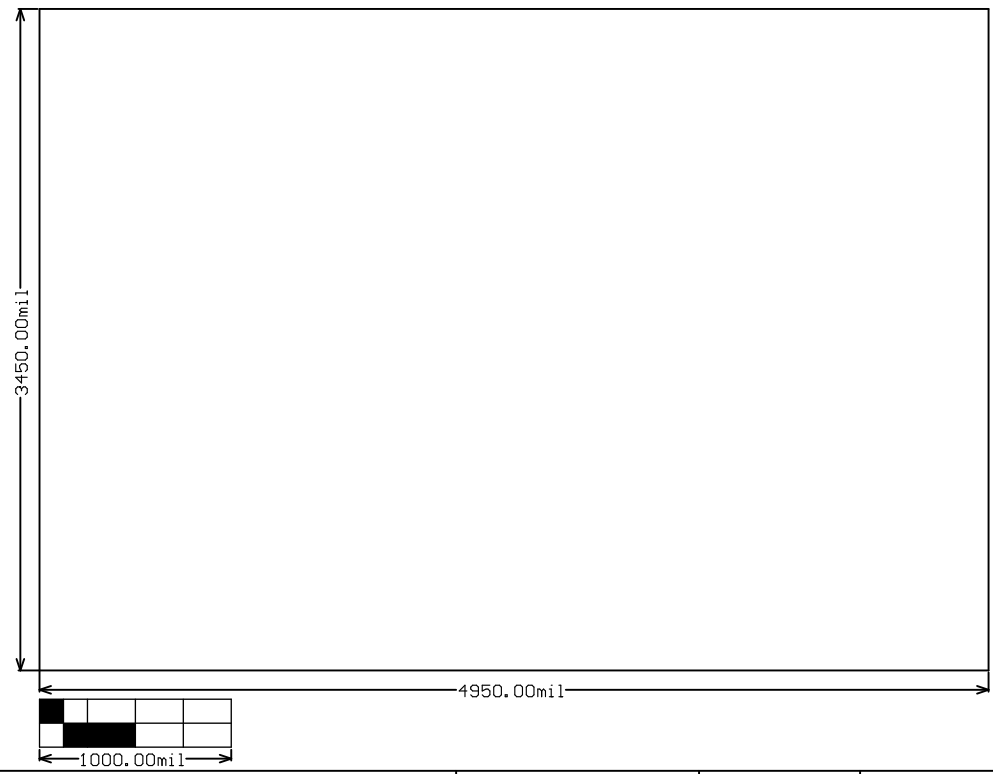


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 6/1/2017 3:00:07 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
A	24	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
V	2	24.00mil (0.610mm)	PTH	Round	Top Layer - Bottom Layer	
X	4	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
D	1	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
X	4	33.00mil (0.838mm)	PTH	Round	Top Layer - Bottom Layer	
X	2	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
□	10	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
B	2	38.00mil (0.965mm)	PTH	Round	Top Layer - Bottom Layer	
+	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
X	2	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	4	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
☆	12	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
○	3	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
V	2	60.00mil (1.524mm)	PTH	Round	Top Layer - Bottom Layer	
☆	3	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
■	7	70.87mil (1.800mm)	PTH	Round	Top Layer - Bottom Layer	
C	2	118.11mil (3.000mm)	PTH	Round	Top Layer - Bottom Layer	
	90 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 6/1/2017	3:00:09 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20795	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 6/1/2017	3:00:11 PM	TEXAS INSTRUMENTS

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